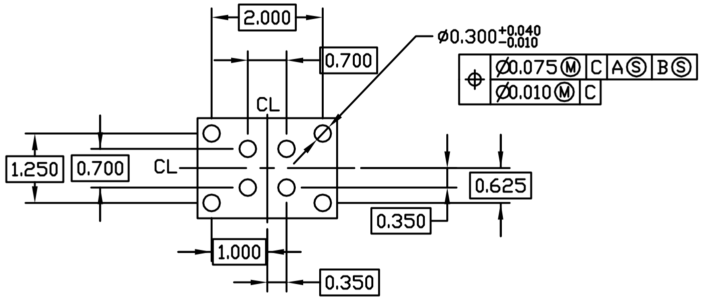
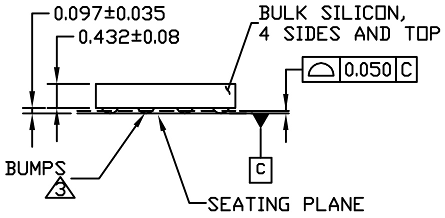
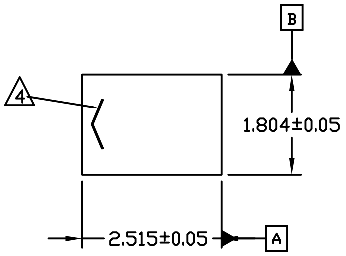


BOTTOM VIEW



SIDE VIEW



PACKAGE OUTLINE

TOP VIEW

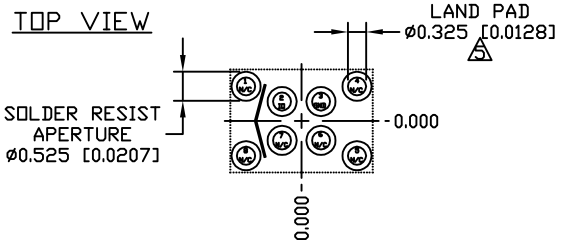
NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. BUMP MATERIAL: 5 Sn / 95 Pb
4. LASER MARK
5. LANDING PAD DIAMETER NOT DEFINED BY SOLDER RESIST; FOR PAD CENTER COORDINATES AND CONNECTIONS, SEE TABLE 1
6. UNDERFILL RECOMMENDED FOR RELIABILITY ON FR4 SUSTRATE
7. ALL DIMENSIONS APPLY TO LEADED (-) PKG. CODES ONLY.
8. PACKAGE CODE: BF823-1

TABLE 1. LAND PAD CONNECTIONS AND CENTER COORDINATES

		MM		INCH	
NUMBER	NAME	X	Y	X	Y
1	N/C	-1	0.625	-0.0394	0.0246
2	I/O	-0.35	0.35	-0.0138	0.0138
3	GND	0.35	0.35	0.0138	0.0138
4	N/C	1	0.625	0.0394	0.0246
5	N/C	1	-0.625	0.0394	-0.0246
6	N/C	0.35	-0.35	0.0138	-0.0138
7	N/C	-0.35	-0.35	-0.0138	-0.0138
8	N/C	-1	-0.625	-0.0394	-0.0246

TOP VIEW



RECOMMENDED SUBSTRATE
LAND PATTERN

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE, 8 BALLS FLIP CHIP,
1.80x2.52x0.43 mm, 0.70mm PITCH

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0284	B	1/1